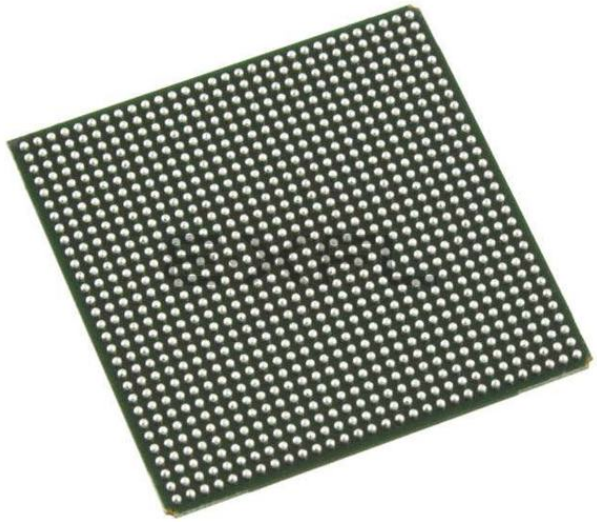
Lattice Semiconductor Corporation - LFX1200B-05F900C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

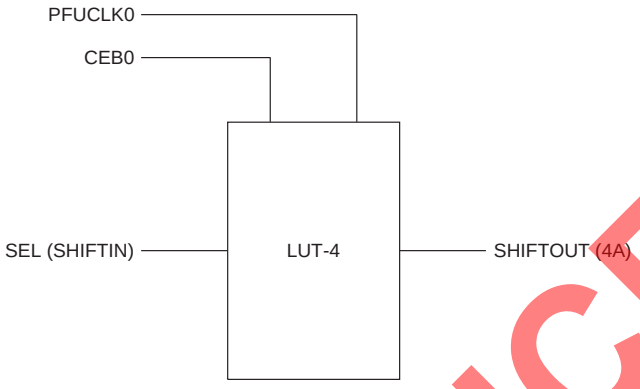
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15376
Total RAM Bits	423936
Number of I/O	496
Number of Gates	1250000
Voltage - Supply	2.3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfx1200b-05f900c

Product Line	Ordering Part Number	Product Status	Reference PCN
LFX125EC (Cont'd)	LFX125EC-03F516C	**Discontinued**	PCN#09-10
	LFX125EC-04F516C		
	LFX125EC-03F516I		
LFX200EB	LFX200EB-03F256C	Active / Orderable	
	LFX200EB-03FN256C		
	LFX200EB-04F256C		
	LFX200EB-04FN256C		
	LFX200EB-05F256C		
	LFX200EB-05FN256C		
	LFX200EB-03F256I		
	LFX200EB-03FN256I		
	LFX200EB-04F256I		
	LFX200EB-04FN256I		
	LFX200EB-03F516C	**Discontinued**	PCN#09-10
	LFX200EB-04F516C		
	LFX200EB-05F516C		
	LFX200EB-03F516I		
	LFX200EB-04F516I		
LFX200EC	LFX200EC-03F256C	**Discontinued**	PCN#09-10
	LFX200EC-03FN256C		
	LFX200EC-04F256C		
	LFX200EC-04FN256C		
	LFX200EC-03F256I		
	LFX200EC-03FN256I		
	LFX200EC-03F516C		
	LFX200EC-04F516C		
	LFX200EC-03F516I		
LFX500EB	LFX500EB-03F516C	**Discontinued**	PCN#09-10
	LFX500EB-04F516C		
	LFX500EB-05F516C		
	LFX500EB-03F516I		
	LFX500EB-04F516I		
	LFX500EB-03F900C		
	LFX500EB-03FN900C		
	LFX500EB-04F900C		
	LFX500EB-04FN900C		
	LFX500EB-05F900C		
	LFX500EB-05FN900C		
	LFX500EB-03F900I		
	LFX500EB-03FN900I		
	LFX500EB-04F900I		
	LFX500EB-04FN900I		
LFX500EC	LFX500EC-03F516C	**Discontinued**	PCN#09-10
	LFX500EC-04F516C		
	LFX500EC-03F516I		

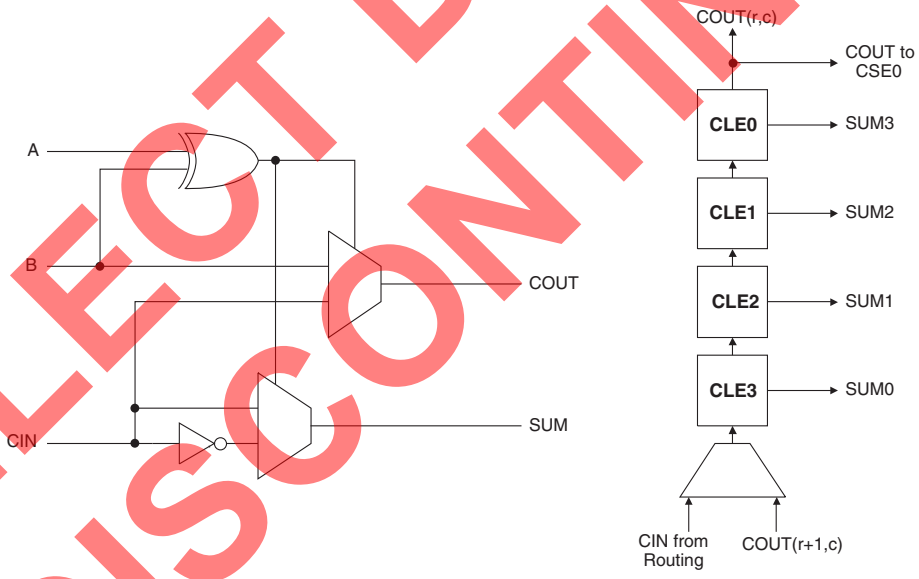
Figure 4. LUT in Shift Register Mode



Carry Chain Generator

The Carry Chain Generator is useful for implementing high-speed arithmetic functions. The CCG consists of a two-input XOR gate whose carryout can be cascaded with the input of the adjacent CCG. As shown in Figure 5, the carryin signal feeds CLE3 of the PFU and is propagated through CLE2 and CLE1 before reaching CLE0. The sum output of the CCG can be fed to the CSE through the WLG. The carryout must propagate to CLE0 for use outside the PFU. The carryout from the PFU can feed the W0 input of CSE0. The CCG also helps to effectively implement wider functions by using its logic elements to expand the capabilities of the LUT-4.

Figure 5. Carry Chain Generator



Wide Logic Generator

The WLG contains the logic necessary to implement wide gate functions. This is made up of a set of multiplexers that are located between the CLE and the CSE. The WLG helps in enhancing the wide gating capability of the PFU. The outputs of each CLE can be cascaded in the WLG to build wide gating functions. Wide multiplexing functions are also possible with a similar use of the WLG. Figure 6 illustrates the WLG.

Table 5. ispXPGA Supported I/O Standards

sysIO Standard	V_{CCO}	V_{REF}	V_{TT}
LVTTL	3.3V	N/A	N/A
LVCMOS-3.3	3.3V	N/A	N/A
LVCMOS-2.5	2.5V	N/A	N/A
LVCMOS-1.8	1.8V	N/A	N/A
PCI	3.3V	N/A	N/A
AGP-1X	3.3V	N/A	N/A
SSTL3, Class I, II	3.3V	1.5V	1.5V
SSTL2, Class I, II	2.5V	1.25V	1.25V
HSTL, Class I	1.5V	0.75V	0.75V
HSTL, Class III	1.5V	0.9V	1.5V
GTL+	N/A	1.0V	1.5V
LVPECL	3.3V	N/A	N/A
LVDS[1]	2.5V	N/A	N/A
BLVDS	2.5V	N/A	N/A

1. V_{CCO} must be 2.5V for high speed serial operations (sysHSI block).

Table 6. Differential Interface Standard Support[1]

		sysIO Buffer Not Using sysHSI Block	sysIO Buffer Using sysHSI Block
LVDS	Driver	Supported with external resistor network	Supported
	Receiver	Supported with standard termination	Supported with standard termination
BLVDS	Driver	Supported with external resistor network	Not supported
	Receiver	Supported (may need termination)	Supported (may need termination)
LVPECL	Driver	Supported with external resistor network	Not supported
	Receiver	Supported with termination	Supported with termination

1. For more information, refer to TN1000, sysIO Usage Guidelines for Lattice Devices.

pattern by a device programmer, securing proprietary designs from competitors. The entire device must be erased in order to erase the security scheme.

Density Shifting

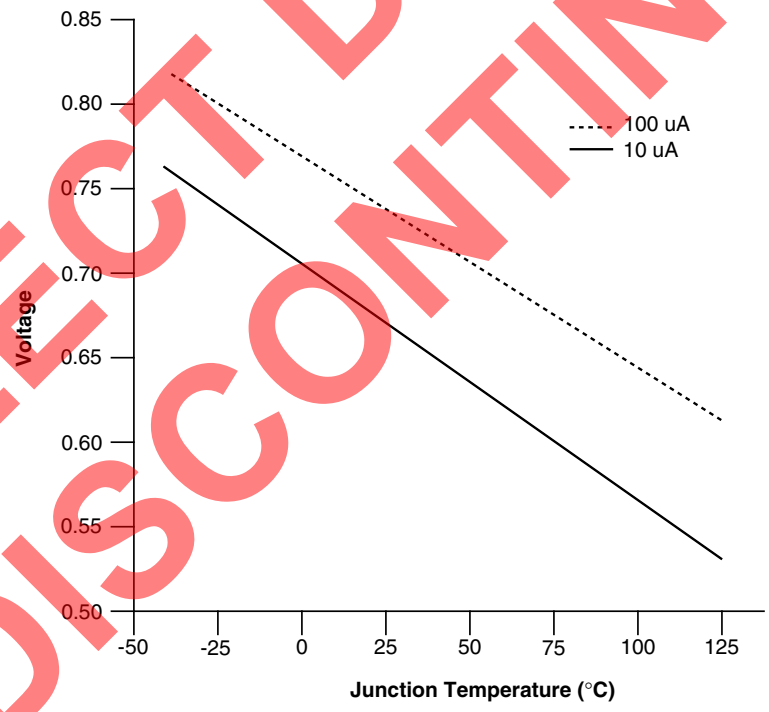
The ispXPGA family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Temperature Sensing Diode

The built-in temperature-sensing diodes allow junction temperature to be measured during device operation. A pair of pins (DXp and DXn) are dedicated for monitoring device junction temperature. The measurement is done by forcing 10 µA and 100 µA current in the forward direction, and then measuring the resulting voltage. The voltage decreases with increasing temperature at approximately 1.64 mV/°C. A typical device with a 85°C junction temperature will measure approximately 593 mV.

The temperature-sensing diode works for the entire operating range as shown in Figure 22 - Sensing Diode Voltage-Temperature Relationship. Refer to the Lattice Thermal Management document for thermal coefficients. Also refer to TN1043, Power Estimation in ispXPGA Devices.

Figure 22. Sensing Diode Voltage-Temperature Relationship



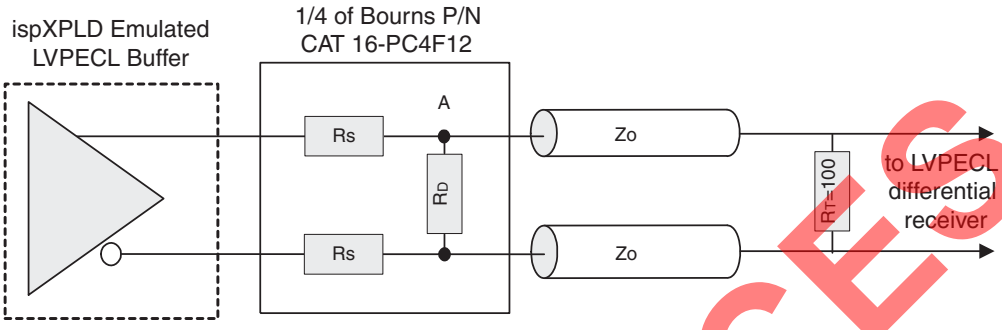
sysIO DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	5.5	0.4	V_{CCO} - 0.4	20, 16, 12, 8, 5.33, 4	-20, -16,-12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCO} - 0.4	16, 12, 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 1.8[1]	-0.3	0.68[3]	1.07[3]	3.6	0.4	V_{CCO} - 0.4	12, 8[1], 5.33, 4	-12, -8[1], -5.33, -4
		0.35V_{CC}	0.65V_{CC}		0.2	V_{CCO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	5.5	0.4	V_{CCO} - 0.4	4	-4
					0.2	V_{CCO} - 0.2	0.1	-0.1
PCI 3.3	-0.3	1.08[3]	1.5[3]	5.5	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
		0.3V_{CCO}	0.5 V_{CCO}					
AGP-1X	-0.3	1.08[3]	1.5[3]	3.6	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
		0.3 V_{CCO}	0.5 V_{CCO}					
SSTL 3 Class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCO} - 1.1	8	-8
SSTL 3 Class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCO} - 0.9	16	-16
SSTL 2 Class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCO} - 0.62	7.6	-7.6
SSTL 2 Class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCO} - 0.43	15.2	-15.2
CTT 3.3	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	V_{REF} - 0.4	V_{REF} + 0.4	8	-8
CTT 2.5	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	V_{REF} - 0.4	V_{REF} + 0.4	8	-8
HSTL Class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	8	-8
HSTL Class III	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	24	-8
GTL+	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.6	N/A	36	N/A

1. Design tool default setting.
2. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed n*8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank
3. Applicable for ispXPGA B devices.

Figure 23. LVPECL Driver with Three Resistor Pack



ispXPGA 125B/C & ispXPGA 125EB/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Conditions	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{CO}	Global Clock Input to Output	PIO Output Register	—	5.3	—	5.7	—	6.6	ns
t_{S}	Global Clock Input Setup	PIO Input Register without input delay	-1.9	—	-1.8	—	-1.5	—	ns
t_{H}	Global Clock Input Hold	PIO Input Register without input delay	2.7	—	2.9	—	3.3	—	ns
t_{SINDLY}	Global Clock Input Setup	PIO Input Register with input delay	3.1	—	3.3	—	3.8	—	ns
t_{HINDLY}	Global Clock Input Hold	PIO Input Register with input delay	0.0	—	0.0	—	0.0	—	
t_{COPLL}	Global Clock Input to Output	PIO Output Register using PLL without delay	—	3.6	—	3.9	—	4.5	ns
t_{SPLL}	Global Clock Input Setup	PIO Input Register without input delay using PLL without delay	0	—	0.1	—	0.3	—	ns
t_{HPLL}	Global Clock Input Hold	PIO Input Register without input delay using PLL without delay	0.9	—	1.0	—	1.2	—	ns
$t_{SINDLYPLL}$	Global Clock Input Setup	PIO Input Register with input delay using PLL without delay	5.1	—	5.5	—	6.3	—	ns
$t_{HINDLYPLL}$	Global Clock Input Hold	PIO Input Register with input delay using PLL without delay	-3.0	—	-2.8	—	-2.4	—	ns

1. Only available for ispXPGA 125B and ispXPGA 125EB (2.5V/3.3V) devices.

Timing v.0.3

ispXPGA 125B/C & ispXPGA 125EB/EC PFU Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Reset/Set								
t_{LASSRO}	Asynchronous Set/Reset to Output	—	1.09	—	1.17	—	1.35	ns
$t_{LASSRPW}$	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t_{LASSRR}	Asynchronous Set/Reset Recovery	—	0.51	—	0.55	—	0.63	ns
t_{LSSR_S}	Synchronous Set/Reset Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t_{LSSR_H}	Synchronous Set/Reset Hold Time	0.03	—	0.03	—	0.03	—	ns

1. Only available for ispXPGA 125B and ispXPGA 125EB (2.5V/3.3V) devices.
2. $t_{LCTHRUL}$ quoted bit by bit.

Timing v.0.3

ispXPGA 125B/C & ispXPGA 125EB/EC PIC Timing Parameters

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Register/Latch Delays								
t_{IO_CO}	Register Clock to Output Delay	—	0.89	—	0.96	—	1.10	ns
t_{IO_S}	Register Setup Time (Data before Clock)	0.05	—	0.05	—	0.06	—	ns
t_{IO_H}	Register Hold Time (Data after Clock)	0.06	—	0.06	—	0.07	—	ns
t_{IOCE_S}	Register Clock Enable Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t_{IOCE_H}	Register Clock Enable Hold Time	0.13	—	0.13	—	0.15	—	ns
t_{IO_GO}	Latch Gate to Output Delay	—	0.68	—	0.73	—	0.84	ns
t_{IOL_S}	Latch Setup Time	0.05	—	0.05	—	0.06	—	ns
t_{IOL_H}	Latch Hold Time	0.06	—	0.06	—	0.07	—	ns
t_{IOLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns
t_{IOASRO}	Asynchronous Set/Reset to Output	—	1.00	—	1.08	—	1.24	ns
$t_{IOASRPW}$	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t_{IOASRR}	Asynchronous Set/Reset Recovery Time	—	0.23	—	0.25	—	0.29	ns
Input/Output Delays								
t_{IOBUF}	Output Buffer Delay	—	0.97	—	1.04	—	1.20	ns
t_{IOIN}	Input Buffer Delay	—	0.57	—	0.61	—	0.70	ns
t_{IOEN}	Output Enable Delay	—	0.53	—	0.57	—	0.66	ns
t_{IODIS}	Output Disable Delay	—	-0.14	—	-0.13	—	-0.11	ns
t_{IOFT}	Feed-thru Delay	—	0.19	—	0.20	—	0.23	ns

1. Only available for ispXPGA 125B and ispXPGA 125EB (2.5V/3.3V) devices.

Timing v.0.3

ispXPGA 500B/C & ispXPGA 500EB/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Conditions	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{CO}	Global Clock Input to Output	PIO Output Register	—	6.4	—	6.9	—	7.9	ns
t_S	Global Clock Input Setup	PIO Input Register without input delay	-2.9	—	-2.7	—	-2.3	—	ns
t_H	Global Clock Input Hold	PIO Input Register without input delay	3.6	—	3.9	—	4.5	—	ns
t_{SINDLY}	Global Clock Input Setup	PIO Input Register with input delay	3.3	—	3.6	—	4.1	—	ns
t_{HINDLY}	Global Clock Input Hold	PIO Input Register with input delay	0.0	—	0.0	—	0.0	—	
t_{COPLL}	Global Clock Input to Output	PIO Output Register using PLL without delay	—	3.2	—	3.4	—	3.9	ns
t_{SPLL}	Global Clock Input Setup	PIO Input Register without input delay using PLL without delay	0.1	—	0.2	—	0.3	—	ns
t_{HPLL}	Global Clock Input Hold	PIO Input Register without input delay using PLL without delay	0.8	—	0.9	—	1.0	—	ns
$t_{SINDLYPLL}$	Global Clock Input Setup	PIO Input Register with input delay using PLL without delay	6.7	—	7.2	—	8.3	—	ns
$t_{HINDLYPLL}$	Global Clock Input Hold	PIO Input Register with input delay using PLL without delay	-4.3	—	-4.0	—	-3.4	—	ns

1. Only available for ispXPGA 500B and ispXPGA 500EB (2.5V/3.3V) devices.

Timing v.0.3

ispXPGA 1200B/C & ispXPGA 1200EB/EC PFU Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Reset/Set								
t_{LASSRO}	Asynchronous Set/Reset to Output	—	1.09	—	1.17	—	1.35	ns
$t_{LASSRPW}$	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t_{LASSRR}	Asynchronous Set/Reset Recovery	—	0.51	—	0.55	—	0.63	ns
t_{LSSR_S}	Synchronous Set/Reset Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t_{LSSR_H}	Synchronous Set/Reset Hold Time	0.03	—	0.03	—	0.03	—	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.
2. $t_{LCTHRUL}$ quoted bit by bit.

Timing v.2.1

ispXPGA 1200B/C & ispXPGA 1200EB/EC PIC Timing Parameters

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Register/Latch Delays								
t_{IO_CO}	Register Clock to Output Delay	—	1.01	—	1.09	—	1.25	ns
t_{IO_S}	Register Setup Time (Data before Clock)	0.05	—	0.05	—	0.06	—	ns
t_{IO_H}	Register Hold Time (Data after Clock)	0.06	—	0.06	—	0.07	—	ns
t_{IOCE_S}	Register Clock Enable Setup Time	-0.03	—	-0.03	—	-0.03	—	ns
t_{IOCE_H}	Register Clock Enable Hold Time	0.13		0.13	—	0.15	—	ns
t_{IO_GO}	Latch Gate to Output Delay	—	0.85	—	0.91	—	1.05	ns
t_{IOL_S}	Latch Setup Time	0.05	—	0.05	—	0.06	—	ns
t_{IOL_H}	Latch Hold Time	0.06	—	0.06	—	0.07	—	ns
t_{IOLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns
t_{IOASRO}	Asynchronous Set/Reset to Output	—	1.17	—	1.26	—	1.45	ns
$t_{IOASRPW}$	Asynchronous Set/Reset Pulse Width	4.19	—	4.50	—	5.18	—	ns
t_{IOASRR}	Asynchronous Set/Reset Recovery Time	—	0.23	—	0.25	—	0.29	ns
Input/Output Delays								
t_{IOBUF}	Output Buffer Delay	—	0.99	—	1.06	—	1.22	ns
t_{IOIN}	Input Buffer Delay	—	0.71	—	0.76	—	0.87	ns
t_{IOEN}	Output Enable Delay	—	0.52	—	0.56	—	0.64	ns
t_{IODIS}	Output Disable Delay	—	-0.11	—	-0.10	—	-0.09	ns
t_{IOFT}	Feed-thru Delay	—	0.19	—	0.20	—	0.23	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.

Timing v.2.1

ispXPGA 1200B/C & ispXPGA 1200EB/EC Timing Adders (Cont.)

Parameter	Description	Base Parameter	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS_33_4mA_out	Using 3.3V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVCMOS_33_5.33mA_out	Using 3.3V CMOS Standard, 5.33mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVCMOS_33_8mA_out	Using 3.3V CMOS Standard, 8mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.7	—	0.7	—	0.7	ns
LVCMOS_33_12mA_out	Using 3.3V CMOS Standard, 12mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVCMOS_33_16mA_out	Using 3.3V CMOS Standard, 16mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVCMOS_33_24mA_out	Using 3.3V CMOS Standard, 24mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
AGP_1X_out	Using AGP 1x Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
CTT25_out	Using CTT 2.5V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
CTT33_out	Using CTT 3.3V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
GTL+_out	Using GTL+	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
BLVDS_out	Using Bus Low Voltage Differential Signaling (BLVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
PCI_out	Using PCI Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.

Timing v.2.1

REFCLK and SS_CLKIN Timing

Symbol	Description	Mode	Condition	Min	Max	Unit
$t_{DREFCLK}$	Frequency Deviation Between TX REFCLK and CDRX REFCLK on One Link	8B10B/ 10B12B		-100	100	ppm
$t_{JPPREFCLK}$	REFCLK, SS_CLKIN Peak-to-Peak Period Jitter	All	Random Jitter		0.01	UIPP
$t_{PWREFCLK}$	REFCLK, SS_CLKIN Pulse Width, (80% to 80% or 20% to 20%).	All	40-100MHz	2		ns
			100-200MHz	1		
$t_{RFREFCLK}$	REFCLK, SS_CLKIN Rise/Fall Time (20% to 80% or 80% to 20%)	All			2	ns

Serializer Timing[2]

Symbol	Description	Mode	Condition	Min	Max	Unit
$t_{JPPSOUT}$	SOUT Peak-to-Peak Output Data Jitter	All	f_{CLK} with no jitter		0.25	UIPP
$t_{JPP8B10B}$	SOUT Peak-to-Peak Random Jitter	8B10B	800 Mbps w/K28.7-		130	ps
	SOUT Peak-to-Peak Deterministic Jitter	8B10B	800 Mbps w/K28.5+		160	ps
t_{RFSOUT}	SOUT Output Data Rise/Fall Time (20%, 80%)	LVDS			700	ps
t_{COSOUT}	REFCLK to SOUT Delay	SS/8B10B		$2Bt^{1}$ + 2	$2Bt^{1}$ +10	ns
		10B12B		$1Bt^{1}$ + 2	$1Bt^{1}$ +10	ns
t_{SKTX}	Skew of SOUT with Respect to SS_CLKOUT	SS			300	ps
$t_{CKOSOUT}$	SS_CLKOUT to bit0 of SOUT	SS		$2Bt^{1}$ - t_{SKTX}	$2Bt^{1}$ + t_{SKTX}	ns
$t_{HSITXDDATAS}$	TXD Data Setup Time	All	Note 3	1.5		ns
$t_{HSITXDDATAH}$	TXD Data Hold Time	All	Note 3		1.0	ns

1. Bt: Bit Time Period. High Speed Serial Bit Time.
2. The SIN and SOUT jitter specifications listed above are under the condition that the clock tree that drives the REFCLK to sysHSI Block is in sysCLOCK PLL BYPASS mode.
3. Internal timing for reference only.

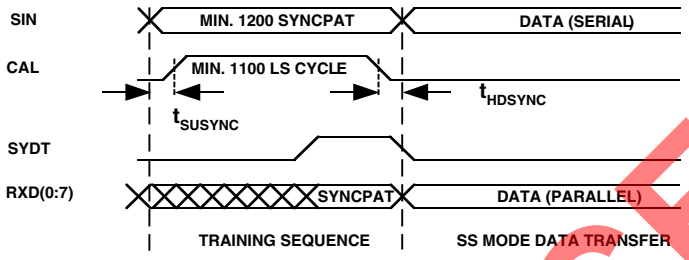
Deserializer Timing

Symbol	Description	Mode	Conditions	Min	Max	Units
f_{DSIN}	SIN Frequency Deviation from REFCLK	8B10B/ 10B12B		-100	100	ppm
eo_{SIN}	SIN Eye Opening Tolerance	All	Notes 1, 2	0.45		UIPP
ber	Bit Error Rate	All			10^{-12}	Bits
$t_{HSIOUTVALIDPRE}$	RXD, SYDT Valid Time Before RECCLK Falling Edge	All	Note 3	$t_{RCP}/2$ - 0.7		ns
$t_{HSIOUTVALIDPOST}$	RXD, SYDT Valid Time After RECCLK Falling Edge	All	Note 3	$t_{RCP}/2$ - 0.7		ns
t_{DSIN}	Bit 0 of SIN Delay to RXD Valid at RECCLK Falling edge	All		1.5 t_{RCP} + 4.5Bt + 3	1.5 t_{RCP} + 4.5Bt + 15	ns

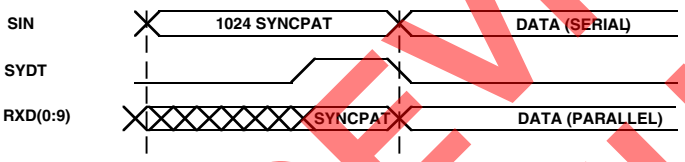
1. Eye opening based on jitter frequency of 100KHz.
2. Lower frequency operation assumes maximum eye closure of 800ps.
3. Internal timing for reference only.

Lock-in Timing

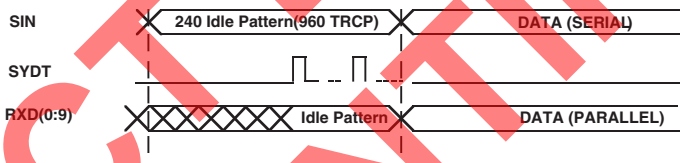
CDRX_SS LOCK-IN (DE-SKEW) TIMING



CDR_10B12B LOCK-IN TIMING

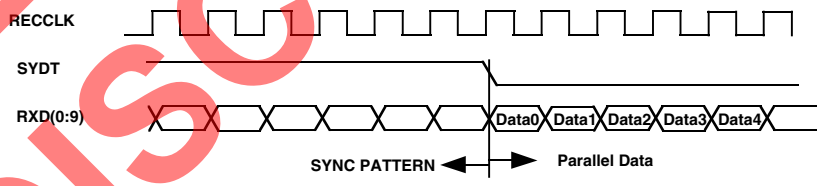


CDR_8B10B LOCK-IN TIMING

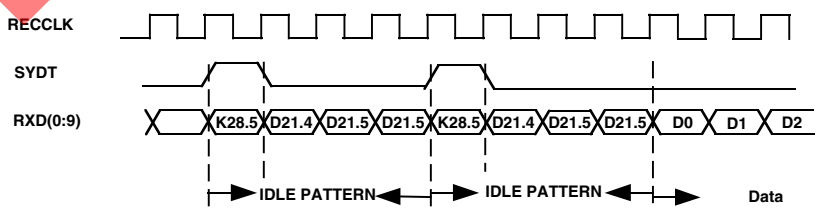


SYDT Timing

SYDT TIMING FOR CDRX_10B12B



SYDT TIMING FOR CDRX_8B10B



ispXP sysCONFIG Port Timing Specifications

Symbol	Timing Parameter	Min.	Typ.	Max.	Units
sysCONFIG Write Cycle Timing					
t_{SUCS}	Input setup time of CS to CCLK rise	10	—	—	ns
t_{HCS}	Hold time of CS to CCLK Rise	0	—	—	ns
t_{SUWD}	Input setup time of write data to CCLK rise	12	—	—	ns
t_{HWD}	Hold time of write data to CCLK rise	0	—	—	ns
t_{PRGM}	Low time to reset device SRAM	5	—	50	ns
t_{WINIT}	INIT pulse width	—	—	5	ms
t_{IODISS}	User I/O disable	—	—	30	ns
t_{IOENSS}	User I/O enable	—	—	30	ns
t_{WH}	Write clock High pulse width	12	—	—	ns
t_{WL}	Write clock Low pulse width	12	—	—	ns
f_{MAXW}	Write f_{MAX}	—	—	33	MHz
sysCONFIG Read Cycle Timing					
t_{HREAD}	Hold time of READ to CCLK rise	0	—	—	ns
t_{SUREAD}	Input setup time of READ High to CCLK rise	30	—	—	ns
t_{RH}	READ clock high pulse width	12	—	—	ns
t_{RL}	READ clock low pulse width	15	—	—	ns
f_{MAXR}	Read f_{MAX}	—	—	33	MHz
t_{CORD}	Clock to out for read data	—	—	25	ns

Boundary Scan Timing

Parameter	Description	Min.	Max.	Units
t_{BTCP}	TCK [BSCAN] Clock Pulse Width	40	—	ns
t_{BTCPH}	TCK [BSCAN] Clock Pulse Width High	20	—	ns
t_{BTCPL}	TCK [BSCAN] Clock Pulse Width Low	20	—	ns
t_{BTS}	TCK [BSCAN] Setup Time	8	—	ns
t_{BTH}	TCK [BSCAN] Hold Time	10	—	ns
t_{BTRF}	TCK [BSCAN] Rise/Fall Time	50	—	mV/ns
t_{BTCO}	TAP Controller Falling Edge of Clock to Valid Output	—	18	ns
$t_{BTCODIS}$	TAP Controller Falling Edge of Clock to Valid Disable	—	18	ns
t_{BTCOEN}	TAP Controller Falling Edge of Clock to Valid Enable	—	18	ns
t_{BTCRS}	BSCAN Test Capture Register Setup Time	8	—	ns
t_{BTCRH}	BSCAN Test Capture Register Hold Time	25	—	ns
t_{BUTCO}	BSCAN Test Update Register, Falling Edge of Clock to Valid Output	—	45	ns
$t_{BTUODIS}$	BSCAN Test Update Register, Falling Edge of Clock to Valid Disable	—	20	ns
$t_{BTUPOEN}$	BSCAN Test Update Register, Falling Edge of Clock to Valid Enable	—	20	ns

ispXPGA Logic Signal Connections: 516-Ball fpBGA (Cont.)

516-Ball BGA Ball	LFX500			LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
-	-	-	-	GND (Bank 0)	-	-	-	-	-
R2	GCLK0	-	LVDS Pair0P	GCLK0	-	LVDS Pair0P	GCLK0	-	LVDS Pair0P
R3	GCLK1	-	LVDS Pair0N	GCLK1	-	LVDS Pair0N	GCLK1	-	LVDS Pair0N
R4	VCCP0	-	-	VCCP0	-	-	VCCP0	-	-
T4	GNDP0	-	-	GNDP0	-	-	GNDP0	-	-
T3	GCLK2	-	LVDS Pair1P	GCLK2	-	LVDS Pair1P	GCLK2	-	LVDS Pair1P
T2	GCLK3	-	LVDS Pair1N	GCLK3	-	LVDS Pair1N	GCLK3	-	LVDS Pair1N
-	-	-	-	GND (Bank 1)	-	-	-	-	-
T1	BK1_IO0	CLK_OUT2	21P	BK1_IO0	CLK_OUT2	13P	BK1_IO0	CLK_OUT2	11P
-	GND (Bank 1)	-	-	-	-	-	-	-	-
U1	BK1_IO1	CLK_OUT3	21N	BK1_IO1	CLK_OUT3	13N	BK1_IO1	CLK_OUT3	11N
U2	BK1_IO2	SS_CLKOUT0P	22P	BK1_IO2	SS_CLKOUT0P	14P	BK1_IO2	SS_CLKOUT0P	12P
-	-	-	-	-	-	-	GND (Bank 1)	-	-
U3	BK1_IO3	SS_CLKOUT0N	22N	BK1_IO3	SS_CLKOUT0N	14N	BK1_IO3	SS_CLKOUT0N	12N
V1	BK1_IO4	PLL_FBK2	23P	BK1_IO4	PLL_FBK2	15P	BK1_IO4	PLL_FBK2	13P
V2	BK1_IO5	PLL_FBK3	23N	BK1_IO5	PLL_FBK3	15N	BK1_IO5	PLL_FBK3	13N
V3	BK1_IO6	-	24P	NC	-	-	NC	-	-
-	GND (Bank 1)	-	-	-	-	-	-	-	-
V4	BK1_IO7	-	24N	NC	-	-	NC	-	-
W1	BK1_IO8	-	25P	NC	-	-	NC	-	-
Y1	BK1_IO9	-	25N	NC	-	-	NC	-	-
W2	BK1_IO10	SS_CLKINOP	26P	BK1_IO6	SS_CLKIN0P	16P	BK1_IO6	SS_CLKIN0P	14P
-	-	-	-	GND (Bank 1)	-	-	-	-	-
W3	BK1_IO11	SS_CLKINON	26N	BK1_IO7	SS_CLKIN0N	16N	BK1_IO7	SS_CLKIN0N	14N
Y2	BK1_IO12		27P	BK1_IO8		17P	BK1_IO8	-	15P
-	-	-	-	-	-	-	GND (Bank 1)	-	-
Y4	BK1_IO13	-	27N	BK1_IO9	-	17N	BK1_IO9	-	15N
Y3	BK1_IO14	-	28P	NC	-	-	NC	-	-
-	GND (Bank 1)	-	-	-	-	-	-	-	-
AA1	BK1_IO15	-	28N	NC	-	-	NC	-	-
AA2	BK1_IO16	-	29P	NC	-	-	NC	-	-
AA3	BK1_IO17	-	29N	NC	-	-	NC	-	-
AB2	BK1_IO18	HSI2A_SOUTP	30P	BK1_IO10	HSI1A_SOUTP	18P/HSI1	BK1_IO10	-	16P
AC2	BK1_IO19	HSI2A_SOUTN	30N	BK1_IO11	HSI1A_SOUTN	18N/HSI1	BK1_IO11	-	16N
AB3	BK1_IO20	PLL_RST2	31P	BK1_IO12	PLL_RST2	19P/HSI1	BK1_IO12	PLL_RST2	17P
AA4	BK1_IO21	PLL_RST3	31N	BK1_IO13	PLL_RST3	19N/HSI1	BK1_IO13	PLL_RST3	17N
AC1	BK1_IO22	HSI2A_SINP	32P	BK1_IO14	HSI1A_SINP	20P/HSI1	NC	-	-
-	GND (Bank 1)	-	-	GND (Bank 1)	-	-	-	-	-
AD1	BK1_IO23	HSI2A_SINN	32N	BK1_IO15	HSI1A_SINN	20N/HSI1	NC	-	-
AE1	BK1_IO24	VREF1	33P/HSI2	BK1_IO16	VREF1	21P/HSI1	BK1_IO14	VREF1	18P
AF1	BK1_IO25		33N/HSI2	BK1_IO17	-	21N/HSI1	BK1_IO15	-	18N
AC3	BK1_IO26	HSI2B_SOUTP	34P/HSI2	BK1_IO18	HSI1B_SOUTP	22P/HSI1	BK1_IO16	-	19P
-	-	-	-	-	-	-	GND (Bank 1)	-	-
AC4	BK1_IO27	HSI2B_SOUTN	34N/HSI2	BK1_IO19	HSI1B_SOUTN	22N/HSI1	BK1_IO17	-	19N
AD2	BK1_IO28	-	35P/HSI2	BK1_IO20	-	23P/HSI1	BK1_IO18	-	20P
AD3	BK1_IO29	-	35N/HSI2	BK1_IO21	-	23N/HSI1	BK1_IO19	-	20N
AE2	BK1_IO30	HSI2B_SINP	36P/HSI2	BK1_IO22	HSI1B_SINP	24P/HSI1	BK1_IO20	-	21P
-	GND (Bank 1)	-	-	GND (Bank 1)	-	-	-	-	-
AF2	BK1_IO31	HSI2B_SINN	36N/HSI2	BK1_IO23	HSI1B_SINN	24N/HSI1	BK1_IO21	-	21N
AD4	BK1_IO32	-	37P/HSI2	NC	-	-	NC	-	-

ispXPGA Logic Signal Connections: 516-Ball fpBGA (Cont.)

516-Ball BGA Ball	LFX500			LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
AJ25	BK3_IO32	-	79P	NC	-	-	NC	-	-
AG24	BK3_IO33	-	79N	NC	-	-	NC	-	-
AK26	BK3_IO34	-	80P	BK3_IO20	-	49P	BK3_IO16	-	41P
-	-	-	-	-	-	-	GND (Bank 3)	-	-
AH25	BK3_IO35	-	80N	BK3_IO21	-	49N	BK3_IO17	-	41N
AJ26	BK3_IO36	-	81P	BK3_IO22	-	50P	BK3_IO18	-	42P
-	-	-	-	GND (Bank 3)	-	-	-	-	-
AH26	BK3_IO37	-	81N	BK3_IO23	-	50N	BK3_IO19	-	42N
AK27	BK3_IO38	-	82P	NC	-	-	NC	-	-
-	GND (Bank 3)	-	-	-	-	-	-	-	-
AJ27	BK3_IO39	-	82N	NC	-	-	NC	-	-
AG26	BK3_IO40	-	83P	BK3_IO24	-	51P	BK3_IO20	-	43P
AH27	BK3_IO41	-	83N	BK3_IO25	-	51N	BK3_IO21	-	43N
AK28	GSR	-	-	GSR	-	-	GSR	-	-
AJ28	DXP	-	-	DXP	-	-	DXP	-	-
AK29	DXN	-	-	DXN	-	-	DXN	-	-
AH29	BK4_IO0	-	84P	BK4_IO0	-	52P/HSI2	BK4_IO0	-	44P
AG28	BK4_IO1	-	84N	BK4_IO1	-	52N/HSI2	BK4_IO1	-	44N
AF27	BK4_IO2	-	85P/HSI3	NC	-	-	NC	-	-
-	GND (Bank 4)	-	-	-	-	-	-	-	-
AF28	BK4_IO3	-	85N/HSI3	NC	-	-	NC	-	-
AJ30	BK4_IO4	-	86P/HSI3	NC	-	-	NC	-	-
AH30	BK4_IO5	-	86N/HSI3	NC	-	-	NC	-	-
AG29	BK4_IO6	-	87P/HSI3	NC	-	-	NC	-	-
AF29	BK4_IO7	-	87N/HSI3	NC	-	-	NC	-	-
AE28	BK4_IO8	-	88P/HSI3	NC	-	-	NC	-	-
AD27	BK4_IO9	-	88N/HSI3	NC	-	-	NC	-	-
AG30	BK4_IO10	HSI3A_SINP	89P/HSI3	BK4_IO2	HSI2A_SINP	53P/HSI2	BK4_IO2	-	45P
-	GND (Bank 4)	-	-	GND (Bank 4)	-	-	-	-	-
AF30	BK4_IO11	HSI3A_SINN	89N/HSI3	BK4_IO3	HSI2A_SINN	53N/HSI2	BK4_IO3	-	45N
AD28	BK4_IO12	-	90P/HSI3	BK4_IO4	-	54P/HSI2	BK4_IO4	-	46P
-	-	-	-	-	-	-	GND (Bank 4)	-	-
AC27	BK4_IO13	-	90N/HSI3	BK4_IO5	-	54N/HSI2	BK4_IO5	-	46N
AE29	BK4_IO14	HSI3A_SOUTP	91P/HSI3	BK4_IO6	HSI2A_SOUTP	55P/HSI2	NC	-	-
AE30	BK4_IO15	HSI3A_SOUTN	91N/HSI3	BK4_IO7	HSI2A_SOUTN	55N/HSI2	NC	-	-
AD29	BK4_IO16	-	92P/HSI3	BK4_IO8	-	56P/HSI2	BK4_IO6	-	47P
AD30	BK4_IO17	VREF4	92N/HSI3	BK4_IO9	VREF4	56N/HSI2	BK4_IO7	VREF4	47N
AC28	BK4_IO18	HSI3B_SINP	93P	BK4_IO10	HSI2B_SINP	57P/HSI2	NC	-	-
-	GND (Bank 4)	-	-	GND (Bank 4)	-	-	-	-	-
AB28	BK4_IO19	HSI3B_SINN	93N	BK4_IO11	HSI2B_SINN	57N/HSI2	NC	-	-
AA27	BK4_IO20	PLL_RST4	94P	BK4_IO12	PLL_RST4	58P/HSI2	BK4_IO8	PLL_RST4	48P
AB29	BK4_IO21	PLL_RST5	94N	BK4_IO13	PLL_RST5	58N/HSI2	BK4_IO9	PLL_RST5	48N
AC29	BK4_IO22	HSI3B_SOUTP	95P	BK4_IO14	HSI2B_SOUTP	59P/HSI2	BK4_IO10	-	49P
AC30	BK4_IO23	HSI3B_SOUTN	95N	BK4_IO15	HSI2B_SOUTN	59N/HSI2	BK4_IO11	-	49N
AA28	BK4_IO24	-	96P	NC	-	-	NC	-	-
Y27	BK4_IO25	-	96N	NC	-	-	NC	-	-
Y28	BK4_IO26	-	97P	NC	-	-	NC	-	-
-	GND (Bank 4)	-	-	-	-	-	-	-	-
AA29	BK4_IO27	-	97N	NC	-	-	NC	-	-
Y29	BK4_IO28	-	98P	BK4_IO16	-	60P	BK4_IO12	-	50P
-	-	-	-	-	-	-	GND (Bank 4)	-	-

ispXPGA Logic Signal Connections: 516-Ball fpBGA (Cont.)

516-Ball BGA Ball	LFX500			LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
J29	BK5_IO22	HSI4B_SOUTP	116P/HSI4	NC	-	-	NC	-	-
-	GND (Bank 5)	-	-	-	-	-	-	-	-
H29	BK5_IO23	HSI4B_SOUTN	116N/HSI4	NC	-	-	NC	-	-
F30	BK5_IO24	-	117P/HSI5	NC	-	-	NC	-	-
G29	BK5_IO25	-	117N/HSI5	NC	-	-	NC	-	-
H28	BK5_IO26	HSI5A_SINP	118P/HSI5	NC	-	-	NC	-	-
H27	BK5_IO27	HSI5A_SINN	118N/HSI5	NC	-	-	NC	-	-
E30	BK5_IO28	-	119P/HSI5	NC	-	-	NC	-	-
F29	BK5_IO29	-	119N/HSI5	NC	-	-	NC	-	-
G28	BK5_IO30	HSI5A_SOUTP	120P/HSI5	NC	-	-	NC	-	-
-	GND (Bank 5)	-	-	-	-	-	-	-	-
G27	BK5_IO31	HSI5A_SOUTN	120N/HSI5	NC	-	-	NC	-	-
E29	BK5_IO32	VREF5	121P/HSI5	BK5_IO16	VREF5	73P/HSI3	BK5_IO14	VREF5	62P/HSI1
F28	BK5_IO33	-	121N/HSI5	BK5_IO17	-	73N/HSI3	BK5_IO15	-	62N/HSI1
D30	BK5_IO34	HSI5B_SINP	122P/HSI5	BK5_IO18	HSI3B_SINP	74P/HSI3	BK5_IO16	HSI1B_SINP	63P/HSI1
-	-	-	-	-	-	-	GND (Bank 5)	-	-
C30	BK5_IO35	HSI5B_SINN	122N/HSI5	BK5_IO19	HSI3B_SINN	74N/HSI3	BK5_IO17	HSI1B_SINN	63N/HSI1
D29	BK5_IO36	-	123P/HSI5	BK5_IO20		75P/HSI3	NC	-	-
D28	BK5_IO37	-	123N/HSI5	BK5_IO21		75N/HSI3	NC	-	-
E28	BK5_IO38	HSI5B_SOUTP	124P/HSI5	BK5_IO22	HSI3B_SOUTP	76P/HSI3	BK5_IO20	HSI1B_SOUTP	65P/HSI1
-	GND (Bank 5)	-	-	GND (Bank 5)	-	-	-	-	-
E27	BK5_IO39	HSI5B_SOUTN	124N/HSI5	BK5_IO23	HSI3B_SOUTN	76N/HSI3	BK5_IO21	HSI1B_SOUTN	65N/HSI1
C29	BK5_IO40	-	125P	BK5_IO24	-	77P/HSI3	BK5_IO18	-	64P/HSI1
B30	BK5_IO41	-	125N	BK5_IO25	-	77N/HSI3	BK5_IO19	-	64N/HSI1
A29	CFG0	-	-	CFG0	-	-	CFG0	-	-
B28	DONE	-	-	DONE	-	-	DONE	-	-
A28	PROGRAMb	-	-	PROGRAMb	-	-	PROGRAMb	-	-
D26	BK6_IO0	INITb	126P	BK6_IO0	INITb	78P	BK6_IO0	INITb	66P
C27	BK6_IO1	CCLK	126N	BK6_IO1	CCLK	78N	BK6_IO1	CCLK	66N
B27	BK6_IO2	-	127P	BK6_IO2	-	79P	BK6_IO2	-	67P
-	GND (Bank 6)	-	-	GND (Bank 6)	-	-	-	-	-
A27	BK6_IO3	-	127N	BK6_IO3	-	79N	BK6_IO3	-	67N
C26	BK6_IO4	CSb	128P	BK6_IO4	CSb	80P	BK6_IO4	CSb	68P
-	-	-	-	-	-	-	GND (Bank 6)	-	-
B26	BK6_IO5	Read	128N	BK6_IO5	Read	80N	BK6_IO5	Read	68N
A26	BK6_IO6	-	129P	NC	-	-	NC	-	-
C25	BK6_IO7	-	129N	NC	-	-	NC	-	-
D24	BK6_IO8	-	130P	NC	-	-	NC	-	-
B25	BK6_IO9	-	130N	NC	-	-	NC	-	-
A25	BK6_IO10	-	131P	NC	-	-	NC	-	-
-	GND (Bank 6)	-	-	-	-	-	-	-	-
C24	BK6_IO11	-	131N	NC	-	-	NC	-	-
D23	BK6_IO12	-	132P	NC	-	-	NC	-	-
B24	BK6_IO13	-	132N	NC	-	-	NC	-	-
C23	BK6_IO14	-	133P	NC	-	-	NC	-	-
A24	BK6_IO15	-	133N	NC	-	-	NC	-	-
C22	BK6_IO16	-	134P	NC	-	-	NC	-	-
B23	BK6_IO17	-	134N	NC	-	-	NC	-	-
B22	BK6_IO18	DATA7	135P	BK6_IO6	DATA7	81P	BK6_IO6	DATA7	69P
-	GND (Bank 6)	-	-	-	-	-	-	-	-
A23	BK6_IO19	DATA6	135N	BK6_IO7	DATA6	81N	BK6_IO7	DATA6	69N

ispXPGA Logic Signal Connections: 680-Ball fpBGA (Cont.)

LFX1200			
680-Ball fpBGA	Signal Name	Second Function	LVDS Pair/sysHSI Reserved[1]
AW35	BK4_IO4	-	126P
AV35	BK4_IO5	-	126N
AV34	BK4_IO6	HSI5A_SINP	127P
AU34	BK4_IO7	HSI5A_SINN	127N
AT34	BK4_IO8	-	128P
AU35	BK4_IO9	-	128N
AT33	BK4_IO10	HSI5A_SOUTP	129P/HSI5
-	GND (Bank 4)	-	-
AU33	BK4_IO11	HSI5A_SOUTN	129N/HSI5
AW34	BK4_IO12	VREF4	130P/HSI5
AV33	BK4_IO13	-	130N/HSI5
AR32	BK4_IO14	HSI5B_SINP	131P/HSI5
AT32	BK4_IO15	HSI5B_SINN	131N/HSI5
AU32	BK4_IO16	-	132P/HSI5
AW33	BK4_IO17	-	132N/HSI5
AV32	BK4_IO18	HSI5B_SOUTP	133P/HSI5
-	GND (Bank 4)	-	-
AV31	BK4_IO19	HSI5B_SOUTN	133N/HSI5
AU31	BK4_IO20	-	134P/HSI5
AW32	BK4_IO21	-	134N/HSI5
AR30	BK4_IO22	HSI6A_SINP	135P/HSI5
AT31	BK4_IO23	HSI6A_SINN	135N/HSI5
AW31	BK4_IO24	-	136P/HSI5
AV30	BK4_IO25	-	136N/HSI5
AT30	BK4_IO26	HSI6A_SOUTP	137P/HSI6
-	GND (Bank 4)	-	-
AT29	BK4_IO27	HSI6A_SOUTN	137N/HSI6
AW30	BK4_IO28	-	138P/HSI6
AU29	BK4_IO29	-	138N/HSI6
AT28	BK4_IO30	HSI6B_SINP	139P/HSI6
AU28	BK4_IO31	HSI6B_SINN	139N/HSI6
AV28	BK4_IO32	-	140P/HSI6
AT27	BK4_IO33	-	140N/HSI6
AU27	BK4_IO34	HSI6B_SOUTP	141P/HSI6
-	GND (Bank 4)	-	-
AV27	BK4_IO35	HSI6B_SOUTN	141N/HSI6
AW28	BK4_IO36	-	142P/HSI6
AR26	BK4_IO37	-	142N/HSI6
AW27	BK4_IO38	-	143P/HSI6
AT26	BK4_IO39	-	143N/HSI6
AV26	BK4_IO40	-	144P/HSI6
AR24	BK4_IO41	-	144N/HSI6
AT25	BK4_IO42	-	145P/HSI6

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
AJ12	BK2_IO43	-	83N	BK2_IO23	-	53N
AD13	BK2_IO44	-	84P	BK2_IO24	-	54P
AE13	BK2_IO45	-	84N	BK2_IO25	-	54N
AK13	BK2_IO46	-	85P	BK2_IO26	-	55P
-	-	-	-	GND (Bank 2)	-	-
AJ13	BK2_IO47	-	85N	BK2_IO27	-	55N
AG13	BK2_IO48	-	86P	BK2_IO28	-	56P
AH13	BK2_IO49	-	86N	BK2_IO29	-	56N
AE14	BK2_IO50	-	87P	BK2_IO30	-	57P
-	GND (Bank 2)	-	-	-	-	-
AF14	BK2_IO51	-	87N	BK2_IO31	-	57N
AG14	BK2_IO52	-	88P	BK2_IO32	-	58P
AH14	BK2_IO53	-	88N	BK2_IO33	-	58N
AJ14	BK2_IO54	-	89P	BK2_IO34	-	59P
-	-	-	-	GND (Bank 2)	-	-
AK14	BK2_IO55	-	89N	BK2_IO35	-	59N
AE15	BK2_IO56	-	90P	BK2_IO36	-	60P
AF15	BK2_IO57	-	90N	BK2_IO37	-	60N
AG15	BK2_IO58	-	91P	BK2_IO38	-	61P
-	GND (Bank 2)	-	-	-	-	-
AH15	BK2_IO59	-	91N	BK2_IO39	-	61N
AJ15	BK2_IO60	-	92P	BK2_IO40	-	62P
AK15	BK2_IO61	-	92N	BK2_IO41	-	62N
-	GND (Bank 2)	-	-	GND (Bank 2)	-	-
-	GND (Bank 3)	-	-	GND (Bank 3)	-	-
AK16	BK3_IO0	-	93P	BK3_IO0	-	63P
AJ16	BK3_IO1	-	93N	BK3_IO1	-	63N
AH16	BK3_IO2	-	94P	BK3_IO2	-	64P
-	GND (Bank 3)	-	-	-	-	-
AG16	BK3_IO3	-	94N	BK3_IO3	-	64N
AF16	BK3_IO4	-	95P	BK3_IO4	-	65P
AE16	BK3_IO5	-	95N	BK3_IO5	-	65N
AK17	BK3_IO6	-	96P	BK3_IO6	-	66P
-	-	-	-	GND (Bank 3)	-	-
AJ17	BK3_IO7	-	96N	BK3_IO7	-	66N
AH17	BK3_IO8	-	97P	BK3_IO8	-	67P
AG17	BK3_IO9	-	97N	BK3_IO9	-	67N
AF17	BK3_IO10	-	98P	BK3_IO10	-	68P
-	GND (Bank 3)	-	-	-	-	-
AE17	BK3_IO11	-	98N	BK3_IO11	-	68N
AH18	BK3_IO12	-	99P	BK3_IO12	-	69P
AG18	BK3_IO13	-	99N	BK3_IO13	-	69N

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
F10	BK7_IO36	-	235P	NC	-	-
G10	BK7_IO37	-	235N	NC	-	-
A8	BK7_IO38	-	236P	NC	-	-
B8	BK7_IO39	-	236N	NC	-	-
D9	BK7_IO40	-	237P	BK7_IO22	-	158P
-	-	-	-	GND (Bank 7)	-	-
E9	BK7_IO41	-	237N	BK7_IO23	-	158N
A7	BK7_IO42	-	238P	BK7_IO24	-	159P
-	GND (Bank 7)	-	-		-	-
B7	BK7_IO43	-	238N	BK7_IO25	-	159N
C8	BK7_IO44	-	239P	BK7_IO26	-	160P
D8	BK7_IO45	-	239N	BK7_IO27	-	160N
A6	BK7_IO46	-	240P	BK7_IO21	-	157N
B6	BK7_IO47	VREF7	240N	BK7_IO20	VREF7	157P
E8	BK7_IO48	-	241P	BK7_IO28	-	161P
F8	BK7_IO49	-	241N	BK7_IO29	-	161N
C7	BK7_IO50	-	242P	BK7_IO30	-	162P
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-
D7	BK7_IO51	-	242N	BK7_IO31	-	162N
E7	BK7_IO52	-	243P	BK7_IO32	-	163P
F7	BK7_IO53	-	243N	BK7_IO33	-	163N
A5	BK7_IO54	-	244P	BK7_IO34	-	164P
B5	BK7_IO55	-	244N	BK7_IO35	-	164N
C6	BK7_IO56	-	245P	BK7_IO36	-	165P
D6	BK7_IO57	-	245N	BK7_IO37	-	165N
D5	BK7_IO58	-	246P	BK7_IO38	-	166P
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-
C5	BK7_IO59	-	246N	BK7_IO39	-	166N
B4	BK7_IO60	-	247P	BK7_IO40	-	167P
A4	BK7_IO61	-	247N	BK7_IO41	-	167N
A3	TDO	-	-	TDO	-	-
B3	VCCJ	-	-	VCCJ	-	-
C4	TDI	-	-	TDI	-	-

1. If a sysHSI Block is used, the indicated sysHSI reserved pins are unavailable for general purpose I/O use.

Revision History (Cont.)

Date	Version	Change Summary
June 2004 (cont.)	08.0 (cont.)	Updated Global Clock Input Setup time specifications.
		Clarification of Serial Out LVDS test condition.
		Clarification of REFCLK, SS_CLKIN peak-to-peak period jitter condition.
		Added sysHSI Reserved pins and footnote.
		Removed industrial ordering part numbers.
July 2004	09.0	Added “E” Series product family.
August 2004	10.0	Final release.
December 2004	10.1	Updated NC Connections table.
April 2005	10.2	Clarification of IDK specification.
April 2005	11.0	Select lead-free packages release.
July 2005	12.0	Added lead-free 516 fpBGA ordering part numbers.
April 2007	13.0	Removed lead-free 680 fpSBGA information from Part Number Description and Ordering Part Number tables. Removed lead-free 516 fpBGA for LFX125 from Ordering Part Number tables.
November 2007	14.0	Removed lead-free 516 fpBGA information from Part Number Description and Ordering Part Number tables.
July 2008	14.1	Added 516 fpBGA package without heat spreader to Part Number Description and Ordering Part Number tables.
February 2010	15.0	Ordering part numbers and ispXPGA Family Selection Guide table have been updated per PCN #03A-10 (discontinuation of the ispXPGA 1200 devices).
		References to "system gates" changed to "functional gates."